

IN THE CLAIMS

Claims 1-21 (Canceled).

Claim 22 (New): An electroconductive sheet, comprising:

a substrate layer of a thermoplastic resin comprising an acrylonitrile-butadiene-styrene copolymer resin and/or a polystyrene resin and a polycarbonate resin; and having laminated on at least one side of the substrate layer;

a surface layer of an electroconductive resin composition comprising a polycarbonate resin and from 5 to 50 wt% of a carbon black and optionally a graft resin.

Claim 23 (New): An electroconductive sheet of claim 22, wherein the substrate layer further comprises a modifer resin selected from the group consisting of a polyethylene resin, a polypropylene resin, an ethylene-propylene copolymer resin, an ethylene-ethylacrylate copolymer resin, an ethylene-vinyl acetate copolymer resin, a polyethylene terephthalate resin, and a polybutylene terephthalate resin.

Claim 24 (New): An electroconductive sheet of claim 22, wherein the polycarbonate resin of the substrate layer is present in an amount of from 1 to 50 wt% based on the thermoplastic resin.

Claim 25 (New): An electroconductive sheet of claim 22, wherein the graft resin comprises an ethylene-glycidylmethacrylate copolymer and an acrylonitrile-butadiene-styrene copolymer; and is present in an amount at most 40 wt% based on the polycarbonate resin of the surface layer.

Claim 26 (New): An electroconductive sheet of claim 22, wherein the carbon black is selected from the group consisting of furnace black, channel black, and acetylene black.

Claim 27 (New): An electroconductive sheet of claim 22, which has a thickness of from 0.1 to 3.0 mm.

Claim 28 (New): An electroconductive sheet of claim 22, wherein the surface layer has a surface roughness of from 0.6 μm to 4.0 μm .

Claim 29 (New): An electroconductive sheet of claim 22, which has a surface resistivity of from 10^2 to $10^{10} \Omega$ on the side on which the surface layer is laminated.

Claim 30 (New): A packaging container for an electronic part, comprising the electroconductive sheet of claim 22.

Claim 31. (New): An injection-molded tray, a vacuum-formed tray, a magazine tape or a carrier tape comprising the electroconductive sheet of claim 22.

Claim 32 (New): An electroconductive sheet, comprising:
a substrate layer of a thermoplastic resin comprising an acrylonitrile-butadiene-styrene copolymer resin and an electroconductive resin composition comprising a polycarbonate resin and from 5 to 50 wt% of a carbon black and having laminated on at least one side of the substrate layer;
a surface layer comprising the electroconductive resin composition.

Claim 33 (New): An electroconductive sheet of claim 32, wherein the substrate layer further comprises a modifier resin selected from the group consisting of a polyethylene resin, a polypropylene resin, an ethylene-propylene copolymer resin, an ethylene-ethylacrylate copolymer resin, an ethylene-vinyl acetate copolymer resin, a polyethylene terephthalate resin, and a polybutylene terephthalate resin.

Claim 34 (New): An electroconductive sheet of claim 32, wherein the electroconductive resin of the substrate layer is present in an amount of from 1 to 50 wt% based on the thermoplastic resin.

Claim 35 (New): An electroconductive sheet of claim 32, wherein the carbon black is selected from the group consisting of furnace black, channel black, and acetylene black.

Claim 36 (New): An electroconductive sheet of claim 32, which has a thickness of from 0.1 to 3.0 mm.

Claim 37 (New): An electroconductive sheet of claim 32, wherein the surface layer has a surface roughness of from 0.6 μm to 4.0 μm .

Claim 38 (New): An electroconductive sheet of claim 32, which has a surface resistivity of from 10^2 to 10^{10} Ω on the side on which the surface layer is laminated.

Claim 39. (New): A packaging container for an electronic part, comprising the electroconductive sheet of claim 32.

Claim 40. (New): An injection-molded tray, a vacuum-formed tray, a magazine tape or a carrier tape comprising the electroconductive sheet of claim 32.

Claim 41 (New): An electroconductive sheet, comprising:

a polycarbonate resin;

5-50 wt% of a carbon black; and optionally

at most 40 wt% of a graft resin, based on the polycarbonate resin.

Claim 42 (New): An electroconductive sheet of claim 41, wherein the polycarbonate resin is selected from the group consisting of an aromatic polycarbonate resin, an aliphatic polycarbonate resin, and an aromatic-aliphatic polycarbonate.

Claim 43 (New): An electroconductive sheet of claim 41, further comprising a modifier resin selected from the group consisting of a polyethylene resin, a polypropylene resin, an ethylene-propylene copolymer resin, an ethylene-ethylacrylate copolymer resin, an ethylene-vinyl acetate copolymer resin, a polyethylene terephthalate resin, and a polybutylene terephthalate resin.

Claim 44 (New): An electroconductive sheet of claim 41, wherein the carbon black is selected from the group consisting of furnace black, channel black, and acetylene black.

Claim 45 (New): An electroconductive sheet of claim 41, wherein the graft resin comprises an ethylene-glycidylmethacrylate copolymer resin and an acrylonitrile-butadiene-styrene copolymer resin.

Claim 46 (New): An electroconductive sheet of claim 41, which has a thickness of from 0.1 to 3.0 mm.

Claim 47 (New): An electroconductive sheet of claim 41, wherein the surface layer has a surface roughness of from 0.6 μm to 4.0 μm .

Claim 48 (New): An electroconductive sheet of claim 41, which has a surface resistivity of from 10^2 to $10^{10} \Omega$ on the side on which the surface layer is laminated.

Claim 49. (New): A packaging container for an electronic part, comprising the electroconductive sheet of claim 41.

Claim 50. (New): An injection-molded tray, a vacuum-formed tray, a magazine tape or a carrier tape comprising the electroconductive sheet of claim 41.

SUPPORT FOR THE AMENDMENT

Support for Claim 22 is found in Example 2, pp. 18-19 and Example 12, pp. 27-28.

Support for Claims 23, 33, and 43 is found on p. 14, ll. 19-27.

Support for Claim 24 is found on p. 9, ll. 14-24.

Support for Claims 25 and 45 is found on p. 5, l. 24 to p. 6, l. 10.

Support for Claims 26, 35, and 44 is found on p. 4, ll. 8-14.

Support for Claims 27, 36, and 46 is found on p. 17, ll. 2-3.

Support for Claims 28, 37, and 47 is found on p. 16, ll. 13-19.

Support for Claim 29, 38, and 48 is found in Table 1, p. 22; Table 2, p. 25; and Table 3, p. 29.

Support for Claims 30, 31, 39, 40, 49, and 50 is found on p. 17, ll. 20-24.

Support for Claim 32 is found in Example 3, pp. 19-20.

Support for Claim 34 is found on p. 9, ll. 14-24.

Support for Claim 41 is found in Examples 9 and 10, p. 26.

Support for Claim 42 is found on p. 3, ll. 20-22.